# AC7913A6 Datasheet

# Zhuhai Jieli Technology Co.,LTD

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### **AC7913A6 Features**

#### High performance 32-bit RISC CPU

- Double core RISC 32-bit CPU(Support FPU)
- 24KB D-Cache 6 way, 32KB I-Cache 8way
- DC-320MHz operation
- 128 Vectored interrupts
- Four Levels interrupt priority

#### Flexible I/O

- 16 GPIO pins
- All GPIO pins can be programmable as input or output individually
- All GPIO pins are internal pull-up/pull-down selectable individually
- CMOS/TTL level Schmitt triggered input
- External wake up/interrupt on all GPIOs

#### **Peripheral Feature**

- FUSB 1.1/HUSB2.0 OTG controller
- Audio interface supports IIS, left adjusted, right adjusted and DSP mode
- Multi-function 32-bit timers, support capture and PWM mode
- 16-bit PWM generator for motor driving
- Three full-duplex advanced UART
- One SPI interface supports host and device mode
- Two SD Card Host controller
- One IIC interface supports host and device mode
- One SPDIF receiving interface without analog amplify
- Quadrate decoder
- Watchdog
- One Crystal Oscillator
- Two channel 16-bit DAC with headphone

#### amplifier

- Three channels Audio 16-bit ADC
- Three channels MIC amplifier
- Two channels analog MUX
- Eleven channels 10-bit ADC
- Power-on reset
- Embedded PMU support low power mode

#### **Bluetooth Feature**

- CMOS single-chip fully-integrated radio and baseband
- Compliant with Bluetooth V2.1(BR+EDR)+
  BLE V5.3 specification
- Bluetooth Piconet and Scatternet support
- Meet class2 and class3 transmitting power requirement
- Support GFSK and  $\pi/4$  DQPSK all paket types
- Provides +15dbm transmitting power
- Receiver with -93dBm sensitivity
- Support a2dp\avctp\avdtp\avrcp\hfp\spp\smp \att\gap\gatt\rfcomm\sdp\l2cap profile

#### **WIFI Feature**

- Support all mandatory IEEE 802.11b data rates of 1, 2, 5.5 and 11 Mbps, all 802.11g payload data rates of 6, 9, 12, 18, 24, 36, 48 and 54 Mbps, as well as 802.11n MCS0~ MCS7, MCS32, 20MHz/40MHz BW, 800ns and 400ns guard interval.
- Support advanced 1x1 802.11n features:
  Full / Half Guard Interval
  Frame Aggregation
  Reduced Inter-frame Space (RIFS)
  Space Time Block Coding (STBC)
  Greenfield mode



- Support WEP/WPA-PSK(TKIP/CCMP) /WPA2-PSCK/AES256/AES128/SHA256 /SHA128
- Support apply to AP/STA
- Transmitter power:

DSSS 1M/S 17 dBm MCS0 16 dBm MCS7 13 dBm

Receiver sensitivity:

DSSS 1M/S -95 dBm MCS0 -92 dBm MCS7 -74 dBm

### **Packages**

QFN40(5mm\*5mm)

### **Temperature**

Operating temperature: -40°C to +85°C

Storage temperature: -65°C to +150°C



# 1. Pin Definition

### 1.1 Pin Assignment



Figure 1-1 AC7913A6 QFN40 Package Diagram



## 1.2 Pin Description

Table 1-1 AC7913A6\_QFN40 Pin Description

PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
1	WFVDD14	P	/	RF Power 1.4V	-
2	XOSCI	I	/	RF OSCI	-
3	XOSCO	О	/	RF OSCO	-
4	IOVDD	P	/	IO Power 3.3V	-
5	PC10	I/O	24/16/8/2.4	GPIO	SD0_CLKD: SD0 Clock(D) SPI1_DOB: SPI1 Data Out(B) ISP_DI_B Q-decoder1 UART2_RXB: Uart2 Data In(B) ADC9: ADC Channel 9 TMR5CK(MCPWM) PWM3: Timer3 PWM Output TOUCH10: Touch Input Channel 10 SDTAP_DATA
6	PC9	I/O	24/16/8/2.4	GPIO	SD0_CMDD: SD0 CMD(D) SPI1_CLKB: SPI1 Clock(B) ISP_CLK_B Q-decoder0 UART2_TXB: Uart2 Data Out(B) ADC8: ADC Channel 8 TMR4CK(MCPWM) TOUCH9: Touch Input Channel 9 SDTAP_CLKA
	PC8	I/O	24/16/8/2.4	GPIO	SD0_DAT0D: SD0 Data0(D) SPI1_DIB: SPI1 Data In(B) SPDIF_B PWMCH2L(MCPWM) CAP5: Timer5 Capture TOUCH8: Touch Input Channel 8
7	PC3	I/O	24/16/8/2.4	GPIO	UART1_TXB: Uart1 Data Out(B) ALNK0_DAT0A: Audio Link0 Data0(A) ALNK1_DAT0A: Audio Link1 Data0(A) SD1_DAT1B: SD1 Data1(B) FPIN6(MCPWM) TMR4: Timer4 Clock In TOUCH3: Touch Input Channel 3



PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
8	PC2	I/O	24/16/8/2.4	GPIO	IIC_SDA_C: IIC SDA(C) ALNK0_LRCKA: Audio Link0 Word Select(A) ALNK1_LRCKA: Audio Link1 Word Select(A) SD1_DAT0B: SD1 Data0(B) PWMCH4L(MCPWM) CAP1: Timer1 Capture TOUCH2: Touch Input Channel 2
9	PC1	I/O	24/16/8/2.4	GPIO	IIC_SCL_C: IIC SCL(C) ALNK0_SCLKA: Audio Link0 Serial Clock(A) ALNK1_SCLKA: Audio Link1 Serial Clock(A) SD1_CLKB: SD1 Clock(B) ADC7: ADC Channel 7 PWM1: Timer1 PWM Output Wakeup11: Port Wakeup 11 TOUCH1: Touch Input Channel 1
10	PC0	I/O	24/16/8/2.4	GPIO	CLKOUT0: Clock Out0 ALNK0_MCKA: Audio Link0 Master Clock(A) ALNK1_MCKA: Audio Link1 Master Clock(A) SD1_CMDB: SD1 CMD(B) ADC6: ADC Channel 6 PWMCH4H(MCPWM) Wakeup10: Port Wakeup 10 TOUCH0: Touch Input Channel 0
	PB8	I/O	24/16/8/2.4	GPIO	SDGAT: SD Power Gate UART1 RTS:Uart1 Receive Bit Stream
11	PB7	I/O	24/16/8/2.4	GPIO	Control  SD0_CLKA: SD0 Clock(A)  SPI1_DOA: SPI1 Data Out(A)  UART2_RXC: Uart2 Data In(C)  ADC5: ADC Channel 5  PWMCH7L(MCPWM)  SDTAP_DATC



PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
12	PB6	I/O	24/16/8/2.4	GPIO	UART1_CTS:Uart1 Transmit Bit Stream Control SD0_CMDA: SD0 CMD(A) SPI1_CLKA: SPI1 Clock(A) UART2_TXC: Uart2 Data Out(C) ADC4: ADC Channel 4 PWMCH7H(MCPWM) Wakeup9: Port Wakeup 9 SDTAP CLKC
13	PB5	I/O	8	GPIO	SD0_DAT0A: SD0 Data0(A) SPI1_DIA: SPI1 Data In(A) FPIN2(MCPWM) CAP0: Timer0 Capture
14	DVDD	P	/	Core Power 1.2V	
15	HUSBDM	I/O	10	USB Negative Data	-X / 6
16	HUSBDP	I/O	10	USB Positive Data	10,
17	DCVDD14	P	/	Core Power 1.4V	-/ 1/2
18	VSS	P	1	Ground	
19	VBAT	P		LDO Power	
20	SW	P	1	DC-DC Switch Pin	-
21	PGND	P	/	PMU Ground	-
22	FUSBDM	I/O	10	USB Negative Data (pull down)	UART1_RXD: Uart1 Data In(D) ISP_DI_A SPI2_DOB: SPI2 Data Out(B) IIC_SDA_A: IIC SDA(A) ADC12: ADC Channel 12 SDTAP_DATB
23	FUSBDP	I/O	10	USB Positive Data (pull down)	UART1_TXD: Uart1 Data Out(D) ISP_CLK_A SPI2_CLKB: SPI2 Clock(B) IIC_SCL_A: IIC SCL(A) ADC13: ADC Channel 13 SDTAP_CLKB
24	PB1	I/O	24/16/8/2.4	GPIO (pull up)	ISP_DO UART0_TXB: Uart0 Data Out(B) ADC3: ADC Channel 3 Long Press reset TMR1: Timer1 Clock In Wakeup8: Port Wakeup 8



PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
	PA7	I/O	24/16/8/2.4	GPIO	SPDIF_C ADC0: ADC Channel 0 PWMCH1H(MCPWM) TMR0: Timer0 Clock In Wakeup3: Port Wakeup 3 SDTAP CLKD
	PA5	I/O	24/16/8/2.4	GPIO	UART0_TXA: Uart0 Data Out(A) AMUX2: Simulator Channel 2 CAP3: Timer3 Capture
25	PA3	I/O	24/16/8/2.4	GPIO	SPI2_CLKC: SPI2 Clock(C) MIC2P: MIC2 P Channel UART0_TXC: Uart0 Data Out(C) PWMCH0H(MCPWM)
	PA2	I/O	24/16/8/2.4	GPIO	MIC0P: MIC0 P Channel TMR0CK(MCPWM)
26	PA4	I/O	24/16/8/2.4	GPIO	CLKOUT1: Clock Out1 SPI2_DOC: SPI2 Data Out(C) MIC2N: MIC2 N Channel UART0_RXC: Uart0 Data In(C) PWMCH0L(MCPWM)
27	PA1	I/O	24/16/8/2.4	GPIO	MIC0N: MIC0 N Channel PWM0: Timer0 PWM Output
28	PA0	I/O	24/16/8/2.4	GPIO	AMUX0: Simulator Channel 0 TMR1CK(MCPWM) Wakeup2: Port Wakeup 2
	DACR	O	/	DAC Right Channel	-
29	DACL	O	1	DAC Left Channel	-
30	DACVDD	P	1	DAC Power	-
31	HPVSS	P	1	Audio Ground	-
32	VCM	P	1	VCM	-
22	AHVDD	P	1	Audio Power	-
33	IOVDD	P	/	IO Power 3.3V	-
34	PH1	I/O	24/16/8/2.4	GPIO	IIC_SDA_D: IIC SDA(D) SPI2_DOA: SPI2 Data Out(A) UART0_RXD: Uart0 Data In(D) PWMCH3L(MCPWM) TOUCH12: Touch Input Channel 12
	PH9	I/O	24/16/8/2.4	GPIO	MIC1P: MIC1 P Channel



PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
					IIC_SCL_D: IIC SCL(D)
					SPI2_CLKA: SPI2 Clock(A)
					UART0_TXD: Uart0 Data Out(D)
35	PH0	I/O	24/16/8/2.4	GPIO	ADC10: ADC Channel 10
33					PWMCH3H(MCPWM)
					Wakeup12: Port Wakeup 12
					TOUCH11: Touch Input Channel 11
	PH8	I/O	24/16/8/2.4	GPIO	MIC1N: MIC1 N Channel
36	VSS	P	/	Ground	-
37	WFVDD14	P	/	RF Power 1.4V	-
38	WFVSS	P	/	RF Ground	
39	WFVDD33A	P	/	RF Power 3.3V	- X
40	WFRF	-	/	RF Antenna	
	PAD	P	/	VSS	



## 2. Electrical Characteristics

## 2.1 Absolute Maximum Ratings

Table 2-1

Symbol	Parameter	Min	Max	Unit
Tamb	Ambient Temperature	-40	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	5.5	V
WFVDD33A	RF Power 3.3V Voltage	-0.3	3.5	V
AHVDD	Audio Power Voltage	-0.3	3.5	V
WFVDD14	RF Power 1.4V Voltage	-0.3	1.55	V
V <sub>3.3IO</sub>	3.3V IO Input Voltage	-0.3	IOVDD+0.3	V

### 2.2 PMU Characteristics

Table 2-2

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
VBAT	Voltage Input	2.2	3.7	5.5	V	_
IOVDD	Voltage output	2.1	3.3	3.5	V	LDO5V = 5V, 200mA loading
DCVDD14	Voltage output	1.2	1.4	1.55	V	LDO mode: 70mA loading DC-DC mode: 120mA loading
DVDD	Voltage output	0.87	1.2	1.32	V	LDO5V=5V, 100mA loading
WFVDD33A	Voltage Input	2.1	3.3	3.5	V	_
AHVDD	Voltage Input	2.1	3.3	3.5	V	_
WFVDD14	Voltage Input	1.2	1.4	1.55	V	_



### 2.3 IO Input/Output Electrical Logical Characteristics

Table 2-3

IO input characteristics								
Symbol	Parameter	Min	Тур	Max	Unit	<b>Test Conditions</b>		
$V_{\rm IL}$	Low-Level Input Voltage	-0.3	-	0.3* IOVDD	V	IOVDD = 3.3V		
$ m V_{IH}$	High-Level Input Voltage	0.7* IOVDD	_	IOVDD+0.3	V	IOVDD = 3.3V		
IO output o	characteristics							
$V_{ m OL}$	Low-Level Output Voltage	_	_	0.33	v	IOVDD = 3.3V		
V <sub>OH</sub>	High-Level Output Voltage	2.7	_	- \$	V	IOVDD = 3.3V		

## 2.4 Internal Resistor Characteristics

Table 2-4

Port	General Output	High Drive	Internal Pull-Up Resistor	Internal Pull-Down Resistor	Comment	
PA,PC,PD, PH, PB1,PB6, PB7,PB8	8mA	24mA	10K	10K	1.PB1&PD0 default pull up 2.FUSBDM & FUSBDP default pull down	
PB5	8mA	_	10K	10K	3. Internal pull-up/pull-down	
FUSBDP FUSBDM	10mA	_	1.5K	15K	resistance   accuracy ±20%	



### 2.5 DAC Characteristics

Table 2-5

Parameter	Min	Тур	Max	Unit	Test Conditions
Frequency Response	20	_	20K	Hz	
THD+N	_	-72	_	dB	1KHz/0dB
S/N	_	99	_	dB	10Kohm loading
Crosstalk	_	-90	_	dB	With A-Weighted Filter
Output Swing	_	0.9	_	Vrms	
					1KHz/-60dB
Dynamic Range	_	93		dB	10Kohm loading
					With A-Weighted Filter
DAC Output Power	15	_		mW	32ohm loading

### 2.6 ADC Characteristics

Table 2-6

Parameter	Min	Тур	Max	Unit	Test Conditions
	A - Lancard				1KHz/-60dB
Dynamic Range		87		dB	10Kohm loading
					With A-Weighted Filter
S/N		90	_	dB	1KHz/0dB
THD+N	_	-72	_	dB	10Kohm loading
Crosstalk		-80	_	dB	With A-Weighted Filter

### 2.7 ESD Protection

**Table 2-7** 

2002								
Parameter	Тур.	Test pin	Reference standard					
Human Body Mode	±4KV	All pins(except WFRF)	JEDEC EIA/JESD22-A114					
Machine Mode	±200V	All pins	JEDEC EIA/JESD22-A115					
Charge Device Model	±1KV	All pins	JEDEC EIA/JESD22-C101F					
T 1	±200mA	All GPIO pins	JEDEC STANDARD					
Latch up	1.5xVopmax	All power pins	NO.78E					

Note: 1.5xVopmax = 1.5 times maximum operating voltage.



# 3. Package Information

### 3.1 QFN40(5mm\*5mm)

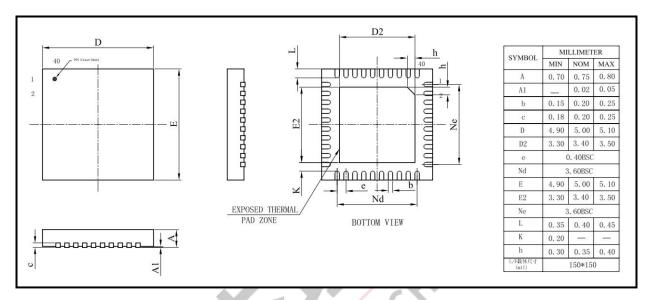
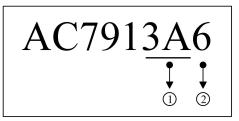


Figure 3-1 AC7913A6\_QFN40 Package



# 4. Package Type Specification



①Represents different chips (different packages or bindings)
Because AC7913A6 has built-in Flash, the pins (PD0, PD1, PD4, PD5, and PD6) of AC7913A0

package for external Flash are changed to bind PB5, PB6, PB7, HUSBDM, HUSBDP. AC7913A6 can be compatible with AC7913A0 applications.

- ②Represents different memory sizes
  - 0: No memory
  - 2: 2Mbit Flash
  - 4: 4Mbit Flash
  - 8: 8Mbit Flash
  - 6: 16Mbit Flash
  - 3: 32Mbit Flash
  - 5: 64Mbit Flash
  - 7: 128Mbit Flash
  - A: 1Mx16 SDRAM
  - B: 4Mx16 SDRAM
  - C: 16M bit PSRAM
  - D: 64M bit PSRAM



## 5. Solder-Reflow Condition

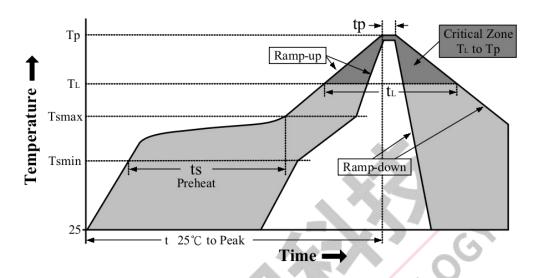


Figure 5-1 Classification Reflow Profile

#### **Classification Profiles**

Table 5-1

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly	
	Temperature Min (T <sub>smin</sub> )	100°C	150°C	
Preheat/Soak	Temperature Max (T <sub>smax</sub> )	150°C	200°C	
	Time (ts) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-180 seconds	
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )		3°C/second max	3°C/second max	
Liquidous temperature (T <sub>L</sub> )		183°C	217°C	
Time (t <sub>L</sub> ) maintained above T <sub>L</sub>		60-150 seconds	60-150 seconds	
Peak package body temperature (Tp)		See Table 6-2	See Table 6-3	
Time within 5°C of actual				
Peak Temperature (tp) <sup>2</sup>		10-30 seconds	20-40 seconds	
Ramp-down rate (T <sub>p</sub> to T <sub>L</sub> )		6°C/second max	6°C/second max	
Time 25°C to p	peak temperature	6 minutes max	8 minutes max	

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5°C of actual peak temperature (tp) specified for the reflow profiles is a "supplier" minimum and "user" maximum.

**SnPb - Classification Temperature** 

Table 5-2

Package Thickness	Volume mm <sup>3</sup> < 350	Volume mm³ ≥350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5℃



**Pb-free - Classification Temperature** Table 5-3

Package Thickness	Volume mm³ < 350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> > 2000
< 1.6mm	260℃	260℃	260°C
1.6 mm - 2.5mm	260℃	250℃	245℃
> 2.5mm	250℃	245℃	245℃





# **6. Revision History**

Date	Revision	Description
2021.10.08	V1.0	Initial Release
2022.07.20	V1.1	Updated parameter

